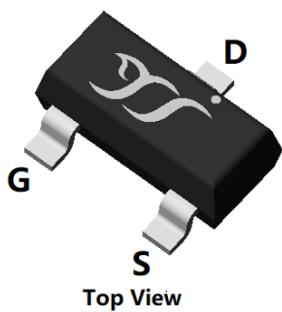
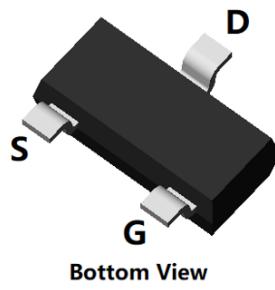


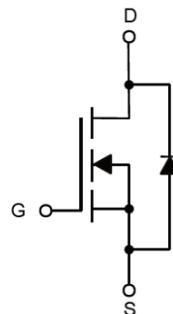
N-Channel Enhancement Mode Field Effect Transistor



Top View



Bottom View

SOT-23


Product Summary

- V_{DS} 30V
- I_D 5.6A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <25mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) <31mohm
- $R_{DS(ON)}$ (at $V_{GS}=2.5V$) <45mohm

General Description

- Trench Power LV MOSFET technology
- High density cell design for low $R_{DS(ON)}$
- High Speed switching
- Part no. with suffix "Q" means AEC-Q101 qualified
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Battery protection
- Load switch
- Power management

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	30	V
Gate-source Voltage		V_{GS}	± 12	V
Drain Current	$T_A=25^\circ C$	I_D	5.6	A
	$T_A=70^\circ C$		4.5	
Pulsed Drain Current ^A		I_{DM}	23	A
Total Power Dissipation	$T_A=25^\circ C$	P_D	1.2	W
	$T_A=70^\circ C$		0.8	W
Thermal Resistance Junction-to-Ambient ^B		$R_{\theta JA}$	104	$^\circ C/W$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ C$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL3400AQ	F2	3400.	3000	30000	120000	7" reel



YJL3400AQ

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS1}	V _{GS} =±12V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.65	0.9	1.5	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5.6A		20	25	mΩ
		V _{GS} =4.5V, I _D =5A		23	31	
		V _{GS} =2.5V, I _D =3A		27	45	
Diode Forward Voltage	V _{SD}	I _S =5.6A, V _{GS} =0V			1.2	V
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHZ		630		pF
Output Capacitance	C _{oss}			55		
Reverse Transfer Capacitance	C _{rss}			71		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =5.6A		17.25		nC
Gate-Source Charge	Q _{gs}			2.1		
Gate-Drain Charge	Q _{gd}			2		
Reverse Recovery Charge	Q _{rr}	I _F =5.6A, di/dt=100A/us		1.1		ns
Reverse Recovery Time	t _{rr}			13.1		
Turn-on Delay Time	t _{D(on)}			4.4		
Turn-on Rise Time	t _r	V _{GS} =10V, V _{DS} =15V, I _D =5.6A R _{GEN} =3Ω		28.2		ns
Turn-off Delay Time	t _{D(off)}			16.2		
Turn-off fall Time	t _f			26		

A. Pulse Test: Pulse Width≤300us, Duty cycle ≤2%.

B. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

■ Typical Performance Characteristics

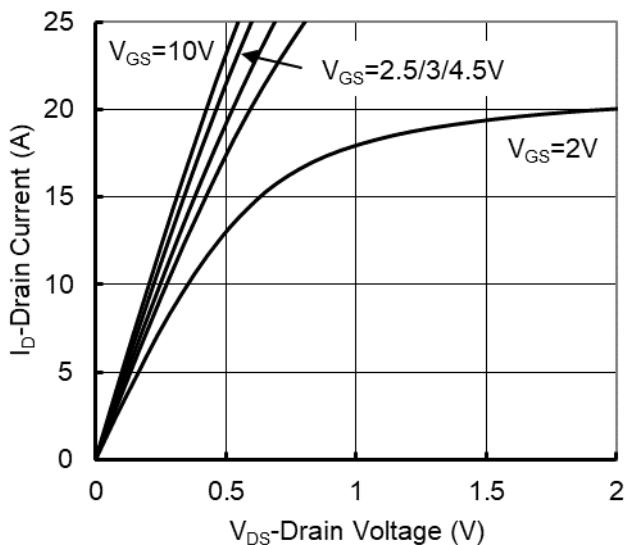


Figure 1. Output Characteristics

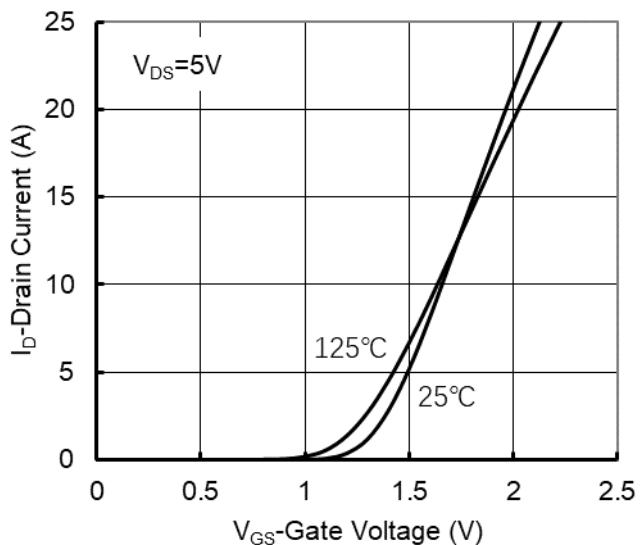


Figure 2. Transfer Characteristics

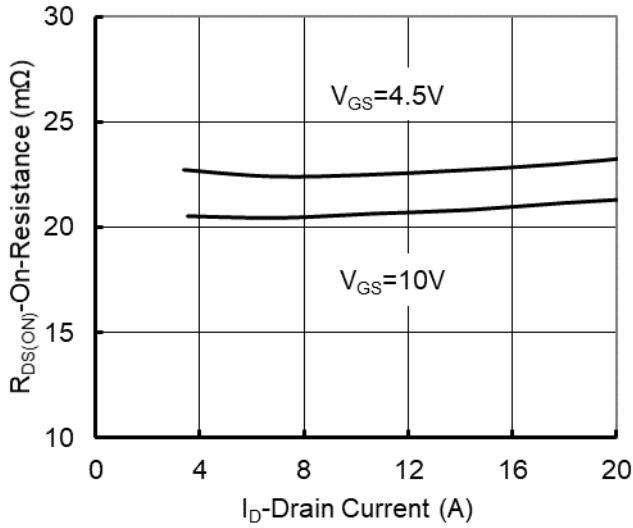


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

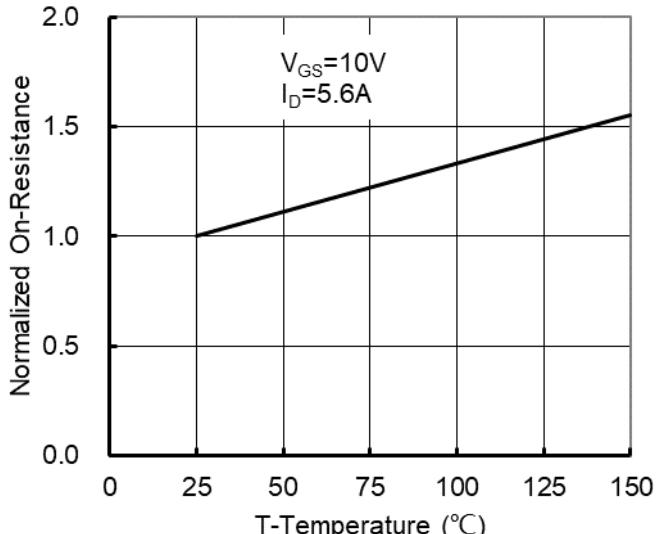


Figure 4: On-Resistance vs. Junction Temperature

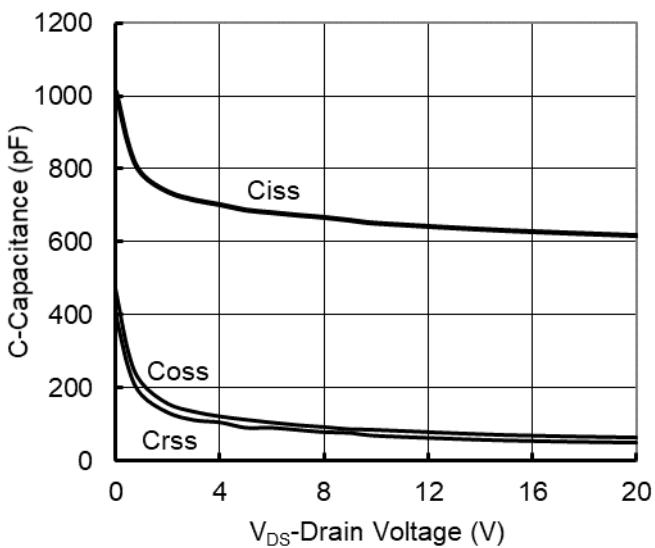


Figure 5. Capacitance Characteristics

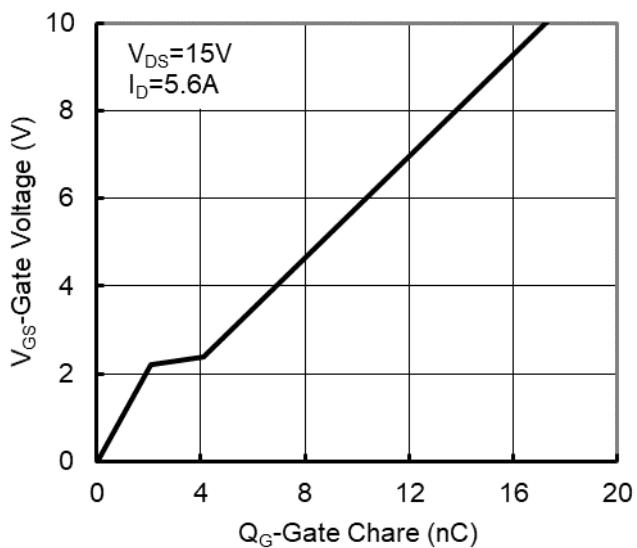
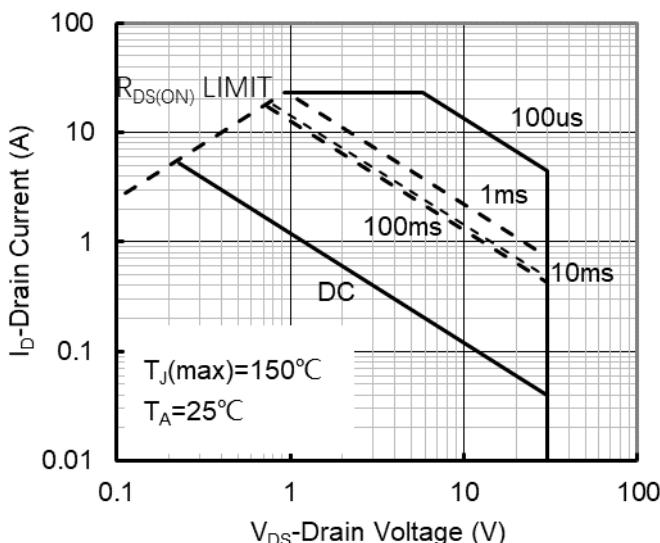
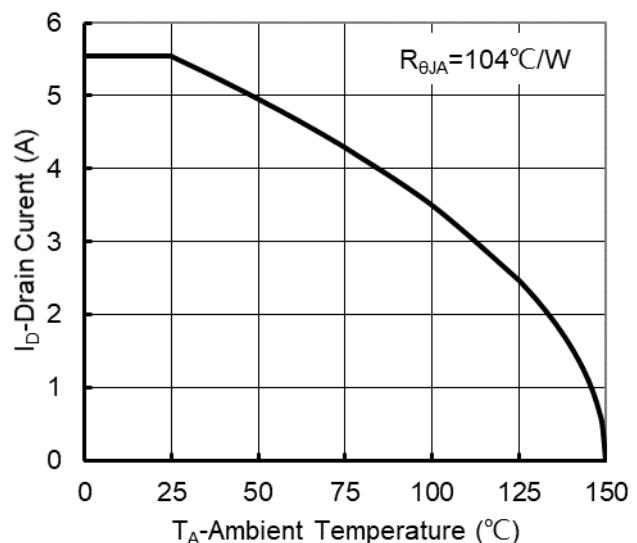
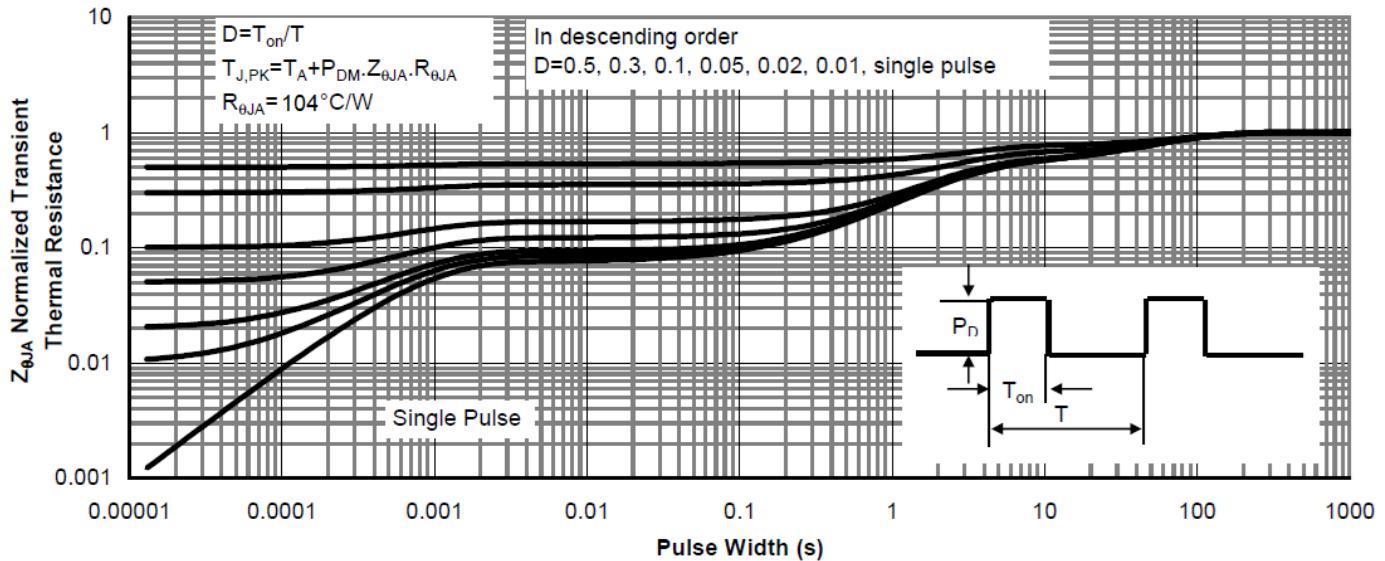
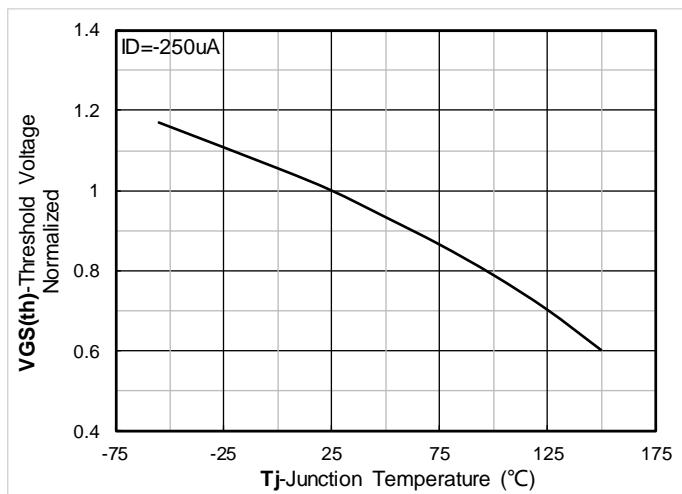
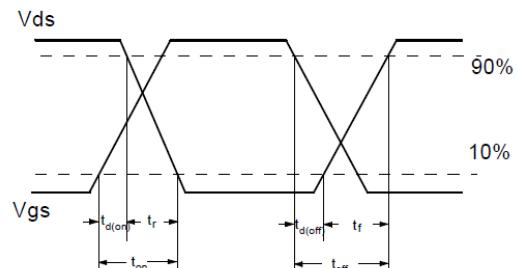
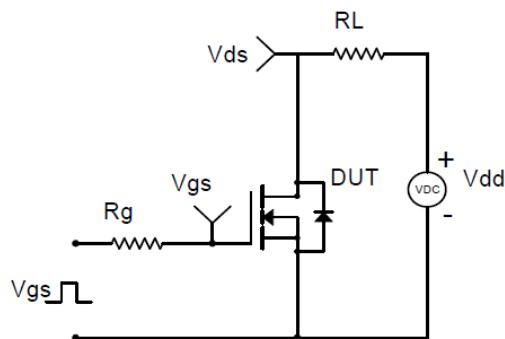
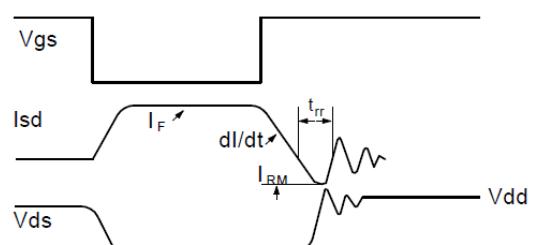
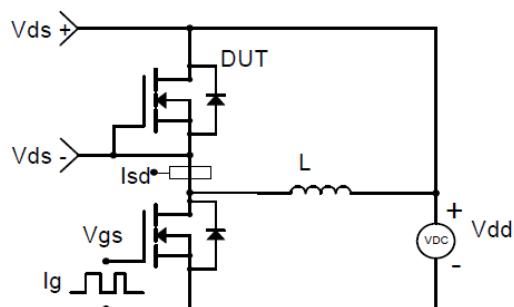


Figure 6. Gate Charge

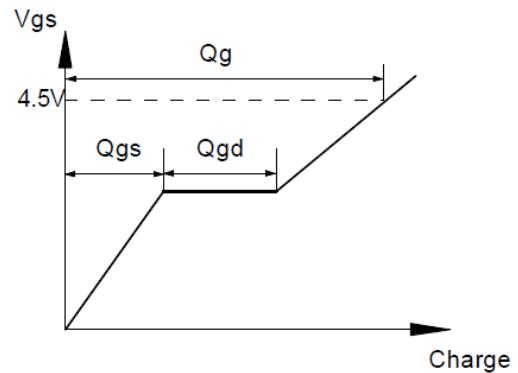
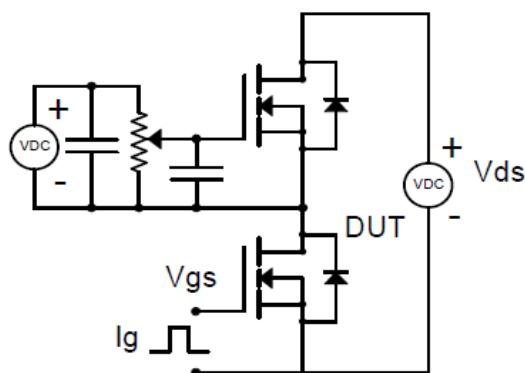

Figure 7. Safe Operation Area

Figure 8. Maximum Continuous Drain Current vs Ambient Temperature

Figure 9. Normalized Maximum Transient Thermal Impedance

Figure 10. Normalized Threshold voltage



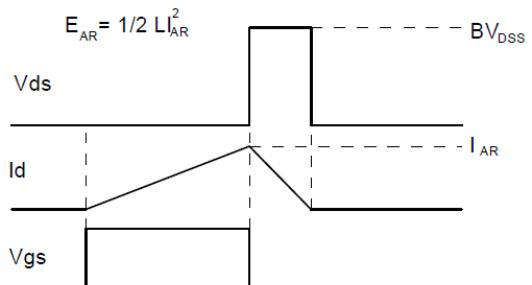
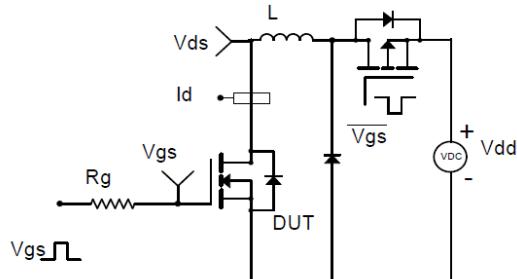
Resistive Switching Test Circuit & Waveforms



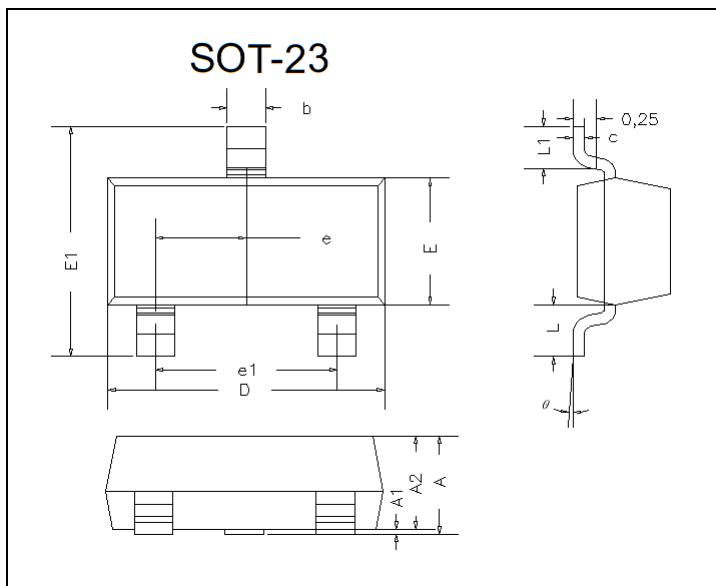
Diode Recovery Test Circuit & Waveforms



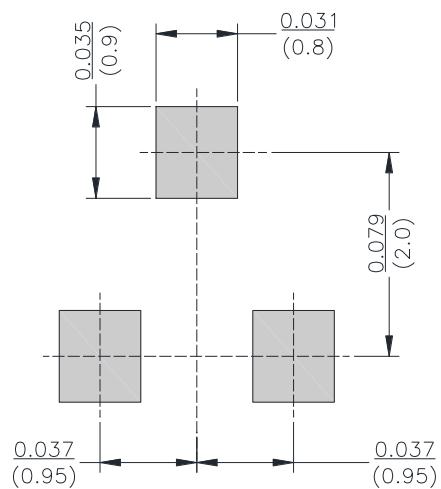
Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

**■ SOT-23 Package information**

DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.035	0.045	0.90	1.15	
A1	0.000	0.004	0.00	0.10	
A2	0.035	0.041	0.90	1.05	
b	0.012	0.020	0.30	0.50	
c	0.004	0.008	0.10	0.20	
D	0.110	0.118	2.80	3.00	
E	0.047	0.055	1.20	1.40	
E1	0.089	0.100	2.25	2.55	
e	0.370TYP		0.95TYP		
e1	0.071	0.079	1.80	2.00	
L	0.220REF		0.55REF		
L1	0.012	0.020	0.30	0.50	
θ	0°	8°	0°	8°	

■ SOT-23 Suggested Pad Layout



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